Pin Out

TOP VIEW

	1	2	3	4	5	6	7	
A	TA6	TA5	TA4	TA3	TA2	TA1	TA0	A
B	TB4	TD3	TD2	TD1	TD0	TA-	TA+	B
C	TB5	TB0	GND	VCC	RS	TB-	TB+	C
D	TB6	TB1	GND	IO VCC	LVDS VCC	TC-	TC+	D
E	TC0	TB2	GND	PLL VCC	R/F	TCLK-	TCLK+	E
F	TC1	TB3	TD4	TD5	TD6	TD-	TD+	F
G	TC2	TC3	TC4	TC5	TC6	CLKIN	/PDWN	G
	1	2	3	4	5	6	7	

Pin Description

Pin Name	Pin #	Type	Description
TA+, TA-	B7, B6	LVDS OUT	LVDS Data Out.
TB+, TB-	C7, C6	LVDS OUT	
TC+, TC-	D7, D6	LVDS OUT	
TD+, TD-	F7, F6	LVDS OUT	
TCLK+, TCLK-	E7, E6	LVDS OUT	LVDS Clock Out.
TA0 ~ TA6	A7,A6,A5,A4,A3,A2,A1	IN	Pixel Data Inputs.
TB0 ~ TB6	C2,D2,E2,F2,B1,C1,D1	IN	
TC0 ~ TC6	E1,F1,G1,G2,G3,G4,G5	IN	
TD0 ~ TD6	B5,B4,B3,B2,F3,F4,F5	IN	
/PDWN	G7	IN	H: Normal operation, L: Power down (All outputs are Hi-Z and all circuits are stand-by mode with minimum current(ITCCS))
RS	C5	IN	LVDS swing mode select. RS: H → LVDS Swing(VOD, see Fig4) 350mV; L → 200mV
R/F	E5	IN	Input Clock Triggering Edge Select. H: Rising edge, L: Falling edge
CLKIN	G6	IN	Clock input.
IO VCC	D4	Power	Power Supply Pin for IO Inputs.
VCC	C4	Power	Power Supply Pin for digital circuitry.
LVDS VCC	D5	Power	Power Supply Pin for LVDS Outputs.
PLL VCC	E4	Power	Power Supply Pin for PLL circuitry.
GND	C3,D3,E3	Ground	Ground Pins for Common.

Absolute Maximum Ratings

Supply Voltage (IO VCC)	-0.3V ~ +4.0V
Supply Voltage (VCC, PLL VCC, LVDS VCC)	-0.3V ~ +2.1V
CMOS/TTL Input Voltage	-0.3V ~ (IO VCC + 0.3V)
LVDS Transmitter Output Voltage	-0.3V ~ (LVDS VCC + 0.3V)
LVDS Total Output Current	-50mA ~ 50mA
Junction Temperature (Tj)	+125°C
Storage Temperature Range	-55°C ~ +125°C
Reflow Peak Temperature / Time	+260°C / 10sec.
Maximum Power Dissipation @+25°C	1.3W

Recommended Operating Conditions

Parameter		Min.	Typ	Max	Units
Supply Voltage (IOVCC)		1.62	1.8/2.5/3.3	3.6	V
Supply Voltage (PLLVCC / LVDSVCC / VCC)		1.62	1.8	1.98	V
Operating Ambient Temperature (Ta)		-40		85	°C
Clock Frequency	Input	8		160	MHz
	LVDS Output	8		160	MHz

Electrical Characteristics

CMOS/TTL DC Specifications

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{IH18}	High Level Input Voltage	IOVCC=1.62~1.98V	0.65 IOVCC		IOVCC+0.3	V
V_{IL18}	Low Level Input Voltage		-0.3		0.35 IOVCC	V
V_{IH25}	High Level Input Voltage	IOVCC=2.3~2.7V	1.7		IOVCC+0.3	V
V_{IL25}	Low Level Input Voltage		-0.3		0.7	V
V_{IH33}	High Level Input Voltage	IOVCC=3.0~3.6V	2.0		IOVCC+0.3	V
V_{IL33}	Low Level Input Voltage		-0.3		0.8	V
I_{INC}	Input Current	VIN=GND~IOVCC	-10		10	μA

LVDS Transmitter DC Specifications

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions		Min.	Typ.	Max.	Units
VOD	Differential Output Voltage	RL=100Ω	Normal swing RS=H	250	350	450	mV
			Reduced swing RS=L	140	200	300	mV
ΔVOD	Change in VOD between complementary output states	RL=100Ω				35	mV
VOC	Common Mode Voltage			1.125	1.25	1.375	V
ΔVOC	Change in VOC between complementary output states					35	mV
I_{OS}	Output Short Circuit Current	V_{OUT}=GND, RL=100Ω				100	mA
I_{OZ}	Output TRI-STATE Current	/PDWN=L, V_{OUT}=GND~LVDSVCC		-20		20	μA

Supply Current

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Condition(*)			Typ.	Max.	Units
I_{TCCW}	Transmitter Supply Current	RL=100Ω CL=5pF	RS=H Normal swing mode	f=37MHz	25	33	mA
				f=71MHz	30	46	mA
				f=160MHz	44	79	mA
			RS=L Reduced swing mode	f=37MHz	19	27	mA
				f=71MHz	24	40	mA
				f=160MHz	38	73	mA
I_{TCCS}	Transmitter Power Down Supply Current	/PDWN = L, All Inputs = L or H			1	50	μA

(a) All Typ. values are at Vcc=1.8V, Ta=25°C . The 16 Grayscale Pattern (Fig1) inputs test for a typical display pattern.

(b) All Max. values are at Vcc=1.98V, Ta=85°C . LVDS Output Full Toggle Pattern (Fig2) produces maximum switching frequency for all the LVDS outputs.

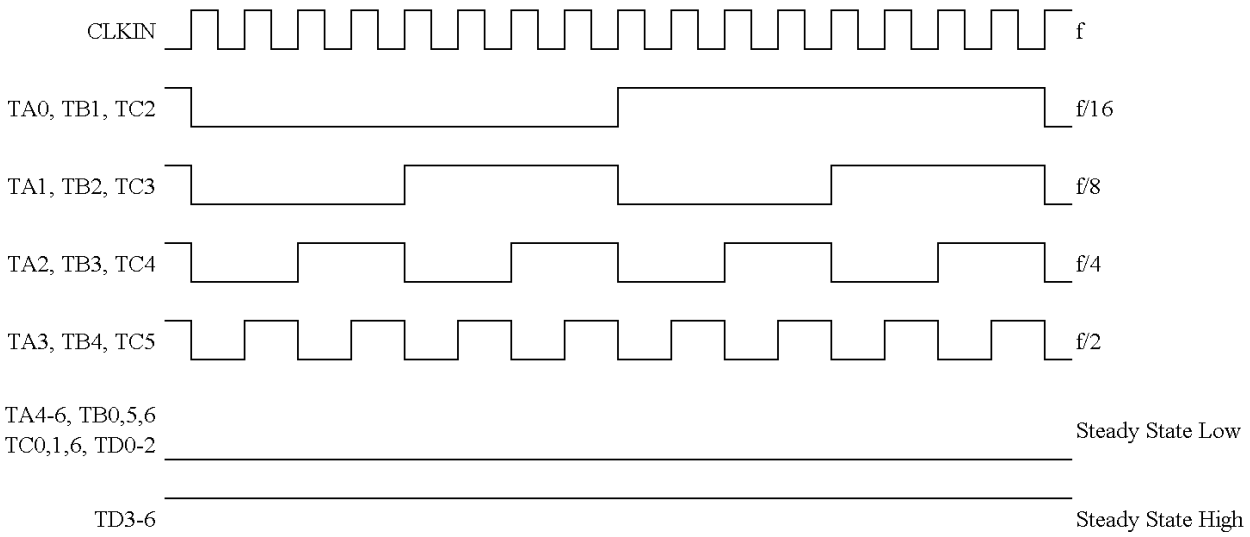


Fig1 16 Grayscale Pattern

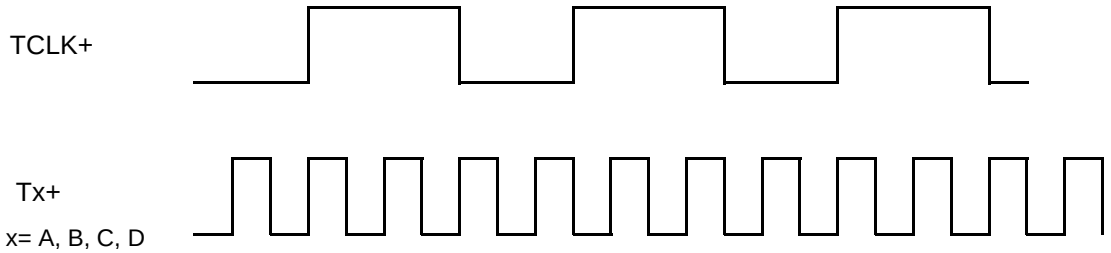


Fig2 LVDS Output Full Toggle Pattern

Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Min.	Typ.	Max.	Units
t_{TCP}	CLK IN Period	6.25	T	125	ns
t_{TCH}	CLK IN High Time	0.35T	0.5T	0.65T	ns
t_{TCL}	CLK IN Low Time	0.35T	0.5T	0.65T	ns
t_{TCD}	CLK IN to TCLK+/- Delay (Fig4)	5T+3.1		5T+8	ns
t_{TS}	TTL Data Setup to CLK IN	0.8			ns
t_{TH}	TTL Data Hold from CLK IN	0.8			ns
t_{LVT}	LVDS Transition Time		0.6	1.5	ns
t_{TOP1}	Output Data Position0 (T=6.25ns~15ns)	-0.15	0.0	+0.15	ns
t_{TOP0}	Output Data Position1 (T=6.25ns~15ns)	$\frac{T}{7}-0.15$	$\frac{T}{7}$	$\frac{T}{7}+0.15$	ns
t_{TOP6}	Output Data Position2 (T=6.25ns~15ns)	$2\frac{T}{7}-0.15$	$2\frac{T}{7}$	$2\frac{T}{7}+0.15$	ns
t_{TOP5}	Output Data Position3 (T=6.25ns~15ns)	$3\frac{T}{7}-0.15$	$3\frac{T}{7}$	$3\frac{T}{7}+0.15$	ns
t_{TOP4}	Output Data Position4 (T=6.25ns~15ns)	$4\frac{T}{7}-0.15$	$4\frac{T}{7}$	$4\frac{T}{7}+0.15$	ns
t_{TOP3}	Output Data Position5 (T=6.25ns~15ns)	$5\frac{T}{7}-0.15$	$5\frac{T}{7}$	$5\frac{T}{7}+0.15$	ns
t_{TOP2}	Output Data Position6 (T=6.25ns~15ns)	$6\frac{T}{7}-0.15$	$6\frac{T}{7}$	$6\frac{T}{7}+0.15$	ns
t_{TPLL}	Phase Lock Loop Set			10.0	ms

AC Timing Diagrams

LVDS Output

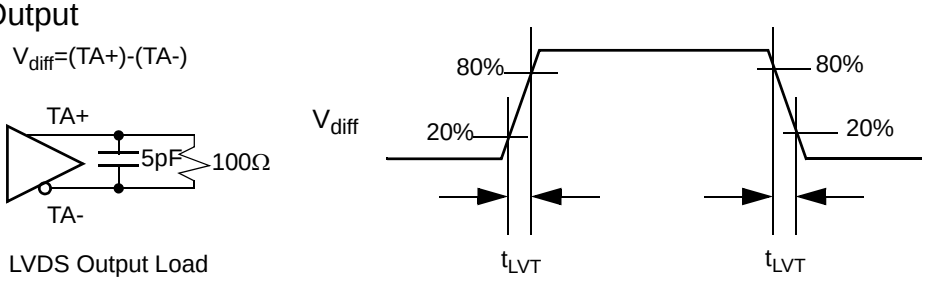


Fig3. LVDS Output Load and Transition Time

AC Timing Diagrams

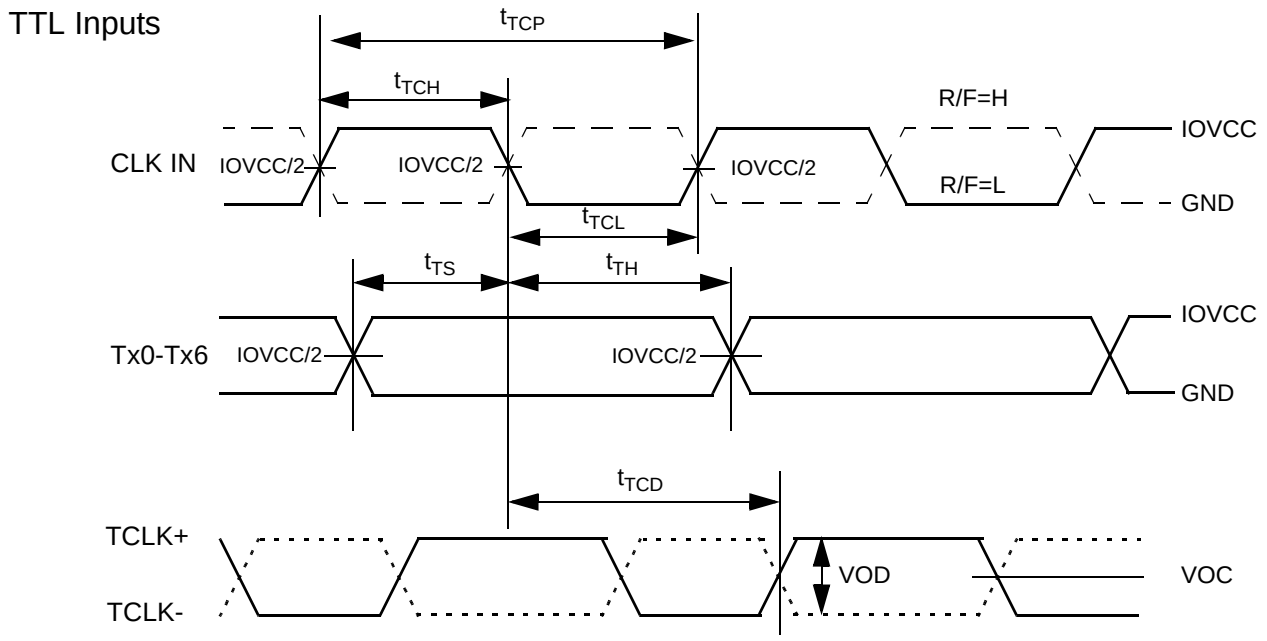


Fig4. CLKIN Period, High/Low Time, Setup/Hold Timing

AC Timing Diagrams

LVDS Output

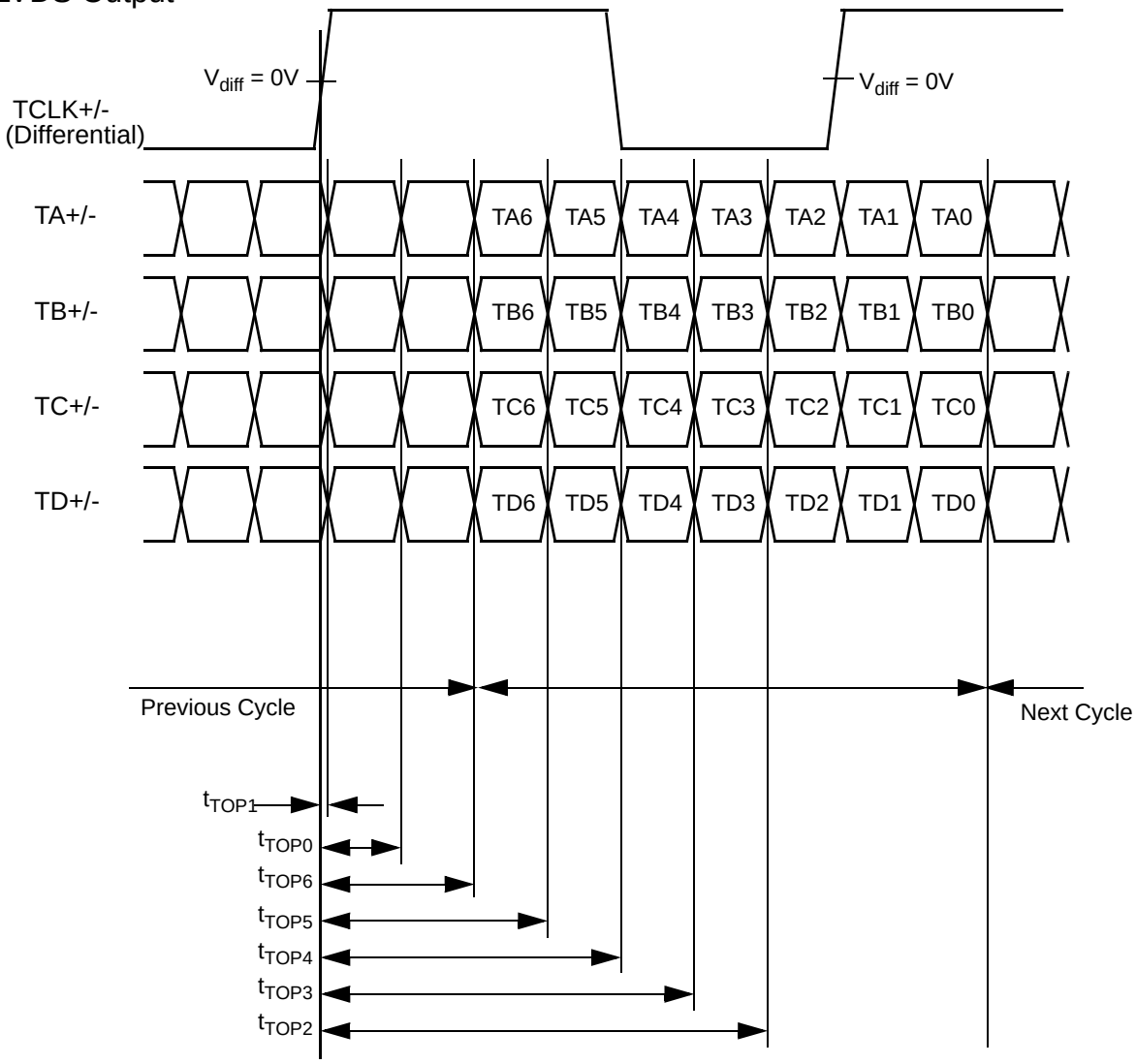


Fig5. LVDS Output Data Position

Phase Lock Loop Set Time

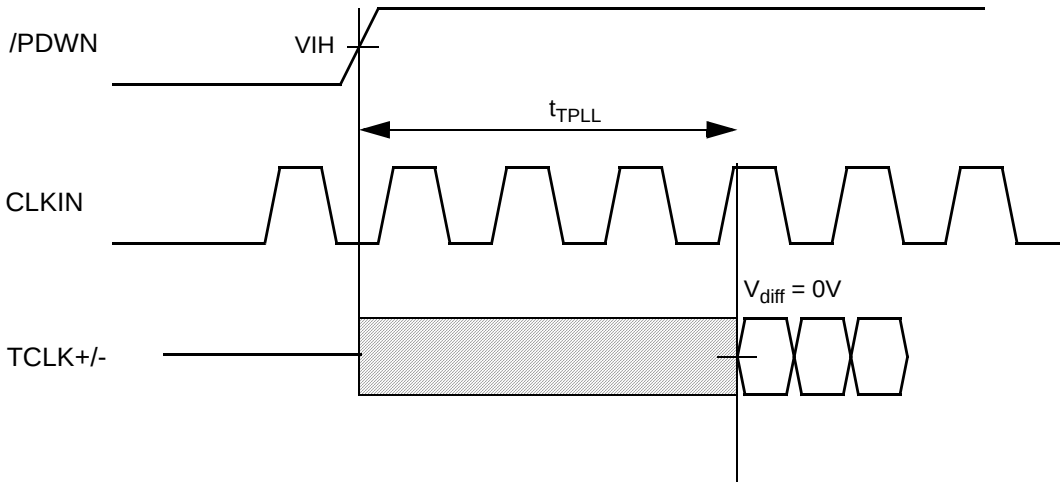


Fig6. PLL Lock Time

Note

1)Cable Connection and Disconnection

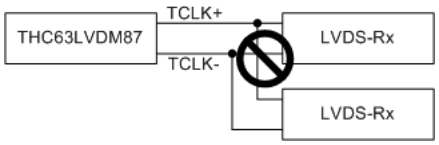
Don't connect and disconnect the LVDS cable, when the power is supplied to the system.

2)GND Connection

Connect the each GND of the PCB which THC63LVDM87 and LVDS-Rx on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

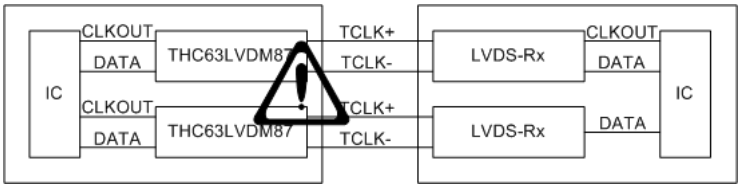
3)Multi Drop Connection

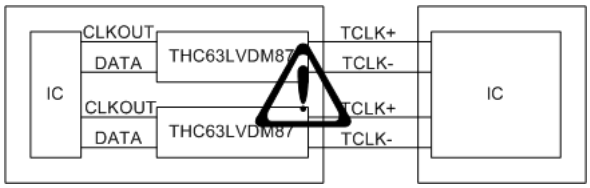
Multi drop connection is not recommended.



4)Asynchronous use

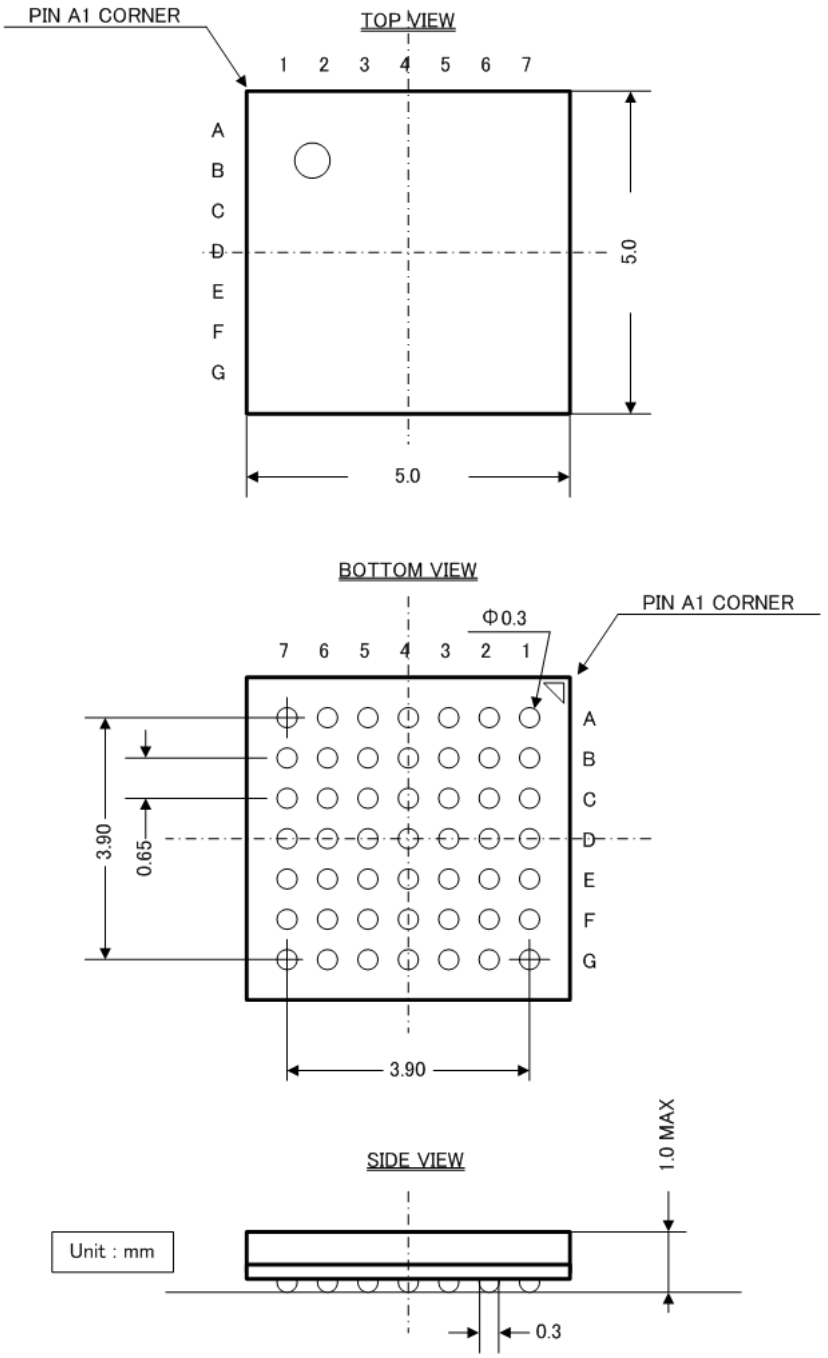
Asynchronous use such as following systems are not recommended.





Package

VFBGA



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